

Electronic Patent Application Fee Transmittal

Application Number:	10789914			
Filing Date:	27-Feb-2004			
Title of Invention:	RESIN COMPOSITION, PREPREG, LAMINATE, AND SEMICONDUCTOR PACKAGE			
First Named Inventor/Applicant Name:	Takeshi Hosomi			
Filer:	Robert M. Siminski/janice ogg			
Attorney Docket Number:	2497-000002/CP			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700